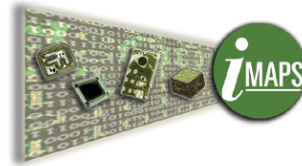


**International Conference and Exhibition
on
Device Packaging**

www.imaps.org/devicepackaging

**Radisson Fort McDowell Resort & Casino
Scottsdale, Arizona - USA
March 17 - 20, 2008**



**Sponsored by
IMAPS**

**International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!**

Announcement and Call for Abstracts

Topical Workshop on

Flip Chip Technologies

***This workshop is being held as a part of the Device Packaging Conference
March 17 - 20, 2008***

Abstract Deadline: November 30, 2007

Technical Chairs:

Beth Keser, Freescale Semiconductor
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Lou Nicholls, Amkor Technology, Inc.
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Flip Chip Technologies Organizing Committee:

Robert Hubbard
Michael Toepper
Thorsten Teutsch
Christo Bojkov
Hong Yang
Chunho Kim

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Flip Chip Technologies Workshop Focus:

The objective of the Flip Chip Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Flip Chip packaging and associated Pb-Free implementation challenges. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to Flip Chip Bumping including Pb-Free versions. **Abstracts are being requested on the following topics:**

- Wafer bumping materials and processes
- Effect of Pb-Free process
- Design for flip chip advancements
- Substrate design for flip chip devices
- Substrates and board technology
- Testing of flip chip devices
- Assembly processes and assembly issues
- Underfill materials & processes & Pb-Free compatibility
- Pb-free / Green flip chip bumping
- Non-solder based flip chips
- Reliability & Pb-Free
- Thermo-mechanical modeling
- End use applications (i.e., OEM products)
- Electro-migration and Inter-metallic effects in Lead-Free
- FC applications

Those wishing to present in the Flip Chip Technologies sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **by November 30, 2007**, using the on-line submittal form at: www.imaps.org/abstracts.htm. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Flip Chip. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 12, 2008 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 17th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than November 30, 2007**.